

**Amendments to the Claims:**

Claim 1 has been amended herein. All of the pending claims 1-4 and 8 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as presently amended.

**Listing of Claims:**

1. (Currently Amended) A system for selectively depositing a material on a previously formed workpiece, comprising:  
a platform for supporting the workpiece including a semiconductor die during a deposition process;  
a sensing system configured to measure over the semiconductor die both an upper surface including a previous material previously deposited thereon and to continuously directly measure a surface level of a material being deposited on the upper surface until the surface level of the material is directly measured to be corresponds to a specific thickness of the material; and  
a deposition system for depositing the material on the workpiece to the specific thickness as monitored by the sensing system.
2. (Previously Presented) The system of claim 1, wherein the deposition system is a spin-coating deposition system.
3. (Previously Presented) The system of claim 2, wherein the sensing system includes a sensor for both measuring the upper surface of the workpiece and for monitoring the surface level of the material deposited on the upper surface of the workpiece.
4. (Previously Presented) The system of claim 2, wherein the sensing system includes a first sensor for measuring the upper surface of the workpiece and a second sensor for

monitoring the surface level of the material deposited on the upper surface of the workpiece.

5-7. (Canceled).

8. (Previously Presented) The system of claim 1, wherein the workpiece is a semiconductor wafer.

9-29. (Canceled).